

ZXTP5401Z 150V, SOT89, PNP High voltage transistor

Summary

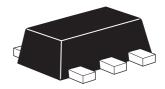
BV_{CEO} > -150V

 $BV_{EBO} > -5V$

 $I_{C(cont)} = -600 mA$

 $P_{D} = 1.2W$

Complementary part number ZXTN5551Z



Description

A high voltage PNP transistor in a small outline surface mount package.

Features

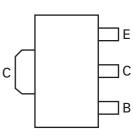
- 150V rating
- SOT89 package

Applications

· High voltage amplification

Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel	
ZXTP5401ZTA	7	12	1000	



Pinout - top view

Device marking

P01

Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	V _{CBO}	-160	V
Collector-emitter voltage	V _{CEO}	-150	V
Emitter-base voltage	V _{EBO}	-5	V
Continuous collector current ^(a)	I _C	-600	mA
Pulsed collector current	I _{CM}	-2	Α
Power dissipation at $T_A = 25^{\circ}C^{(a)}$	P_{D}	1.2	W
Linear derating factor		9.6	mW/°C
Operating and storage temperature range	T _j , T _{stg}	-55 to 150	°C

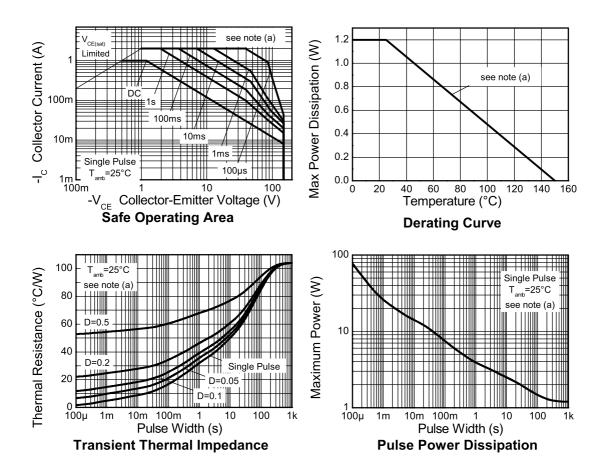
Thermal resistance

Parameter	Symbol	Limit	Unit
Junction to ambient ^(a)	$R_{\Theta JA}$		°C/W

NOTES:

(a) For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz weight copper, in still air conditions.

Typical characteristics



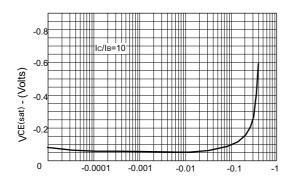
Electrical characteristics (at T_{amb} = 25°C unless otherwise stated)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Collector-base breakdown voltage	BV _{CBO}	-160	-270		V	I _C = -100μA
Collector-emitter breakdown voltage (base open)	BV _{CEO}	-150	-240		V	I _C = -1mA (*)
Emitter-base breakdown voltage	BV _{EBO}	-5	-8.1		V	$I_E = -10\mu A$
Collector cut-off current	I _{CBO}		<-1	-50	nA	V _{CB} = -120V
				-50	μΑ	$V_{CB} = -120V, T_{amb} = 100^{\circ}C$
Collector-emitter saturation	V _{CE(sat)}		-50	-200	mV	$I_C = -10 \text{mA}, I_B = -1 \text{mA}^{(*)}$
voltage			-70	-500	mV	$I_C = -50 \text{mA}, I_B = -5 \text{mA}^{(*)}$
Base-emitter saturation	V _{BE(sat)}		-700	-1000	mV	$I_C = -10 \text{mA}, I_B = -1 \text{mA}^{(*)}$
voltage			-750	-1000	mV	$I_C = -50 \text{mA}, I_B = -5 \text{mA}^{(*)}$
Static forward current	h _{FE}	50	135			$I_C = -1 \text{mA}, V_{CE} = -5 V^{(*)}$
transfer ratio		60	135	240		$I_C = -10 \text{mA}, V_{CE} = -5 V^{(*)}$
		50	130			$I_C = -50 \text{mA}, V_{CE} = -5V^{(*)}$
Transition frequency	f _T		100		MHz	I _C = -10mA, V _{CE} = -10V f = 100MHz
Output capacitance	C _{OBO}			6	pF	V _{CB} = -10V, f = 1MHz ^(*)
Delay time	t _(d)		386		ns	$V_{CC} = -10V. I_{C} = -100mA,$
Rise time	t _(r)		202		ns	$I_{B1} = I_{B2} = -10 \text{mA}$
Storage time	t _(s)		1720		ns	
Fall time	t _(f)		275		ns	

NOTES:

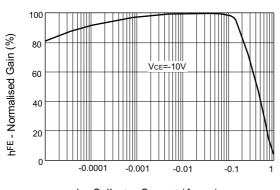
^(*) Measured under pulsed conditions. Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.

Charateristics



Ic - Collector Current (Amps)

VCE(sat) v IC



Ic - Collector Current (Amps)

hFE v IC



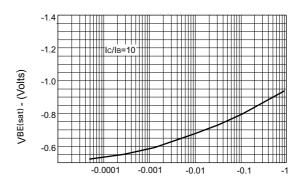
Ic - Collector Current (Amps)

-0.01

-0.1

-0.001

VBE(on) v IC



Ic - Collector Current (Amps)

VBE(sat) v IC

VBE - (Volts)

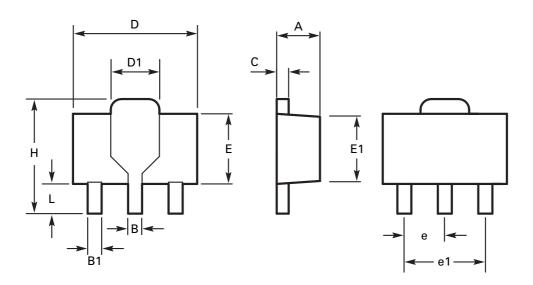
-0.8

-0.6

ZXTP5401Z

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Package outline - SOT89



DIM	Millin	neters	Inc	hes	DIM	Millimeters		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
Α	1.40	1.60	0.550	0.630	Е	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118	BSC
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.52	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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